

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

26. (currently amended) A method of depositing a conductive material on a workpiece and cleaning the workpiece in a chamber, the method comprising the steps of:

lowering the workpiece into a lower section of the chamber;
depositing the conductive material on the workpiece in the lower section of the chamber;
raising the workpiece from the lower section to an upper section of the chamber;
positioning a movable guard between the lower section and the upper section; and
cleaning the workpiece with a liquid in the upper section.

27. (original) A method according to claim 26, wherein the lowering and raising steps comprise the step of providing a workpiece holder, wherein the workpiece holder is lowered and raised using a moveable shaft attached to the workpiece holder.

28. (original) A method according to claim 26, wherein the depositing step further comprises the step of depositing the conductive material using an electro chemical mechanical deposition process.

29. (original) A method according to claim 26, wherein the cleaning step further comprises the steps of:

spinning the workpiece about a first axis;
providing a cleaning solution to the workpiece; and
drying the workpiece by spinning the workpiece.

30. (original) A method according to claim 29, wherein the providing step further comprises spraying the cleaning solution from a plurality of nozzles positioned on the inner walls of the upper chamber.

31. (original) A method according to claim 29, wherein the moveable guard comprises a plurality of flaps connected to linkage rollers and wherein the providing step further comprises spraying the cleaning solution from a plurality of sprayers positioned in the upper surfaces of the plurality of flaps.

32. (original) A method according to claim 29, wherein the moveable guard comprises a flexible guard attached to a guard support.

33. (original) A method according to claim 32, wherein the guard support comprises a plurality of cords coupled to a plurality of rollers.

34. (original) A method according to claim 33, wherein the flexible guard is adapted to move into and out of the chamber using the guard support.

35. (original) A method according to claim 29 further comprising a slit in an inner wall and a housing such that one end of the flexible guard can be positioned within the slit and the other end can be positioned within the housing.

36. (original) A method according to claim 29, wherein after the cleaning solution has been provided to the workpiece, the solution is flowed out the chamber using the moveable guard.

37. (original) A method according to claim 29, wherein the drying step further comprises blowing a dry gas to the workpiece.

38. (original) A method according to claim 26, wherein the step of positioning the moveable guard includes the step of positioning the guard at an angle from a horizontal plane.

39. (original) A method according to claim 38, wherein the angle is between 5 -60 degrees.

92 (new) A method of depositing a conductive material on a surface of a semiconductor workpiece and cleaning a top surface of the conductive material in a chamber comprising the steps:

depositing the conductive material on the surface of the semiconductor workpiece in a lower section of the chamber;

raising the workpiece to an upper section of the chamber;

separating the lower section and the upper section with a movable guard; and

cleaning the top surface of the workpiece with a cleaning liquid in the upper section.

93. (new) A method according to claim 92 further comprising the step of directing the cleaning liquid away from the lower section of the chamber to a reservoir.

94. (new) A method according to claim 93, wherein the step of directing includes isolating the cleaning liquid from solution contained in the lower section to prevent contamination of the solution by the cleaning liquid.

95. (new) A method according to claim 92, wherein the movable guard includes a single guard and the step of separating includes sliding the single guard between the lower section and the upper section of the chamber.

96. (new) A method according to claim 92, wherein the movable guard includes a first guard flap and a second guard flap and the step of separating includes closing the first guard flap and the second guard flap.

97. (new) A method according to claim 92, wherein the step of depositing includes electro chemical deposition.